



INSTALLATION AND OPERATION

USER MANUAL

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UM980

BDS/GPS/GLONASS/Galileo/QZSS

All-constellation Multi-frequency

High Precision RTK Positioning Module

Revision History

Version	Revision History	Date
R1.0	First release	2022-08
R1.1	<ul style="list-style-type: none">• If hot start is not used, V_BCKP should be connected to VCC;• Update the IO threshold in Table 2-4;• Add section 3.1: UM980 minimal design;• Update the recommended thickness of the stencil in Chapter 4	2022-10
R1.2	<ul style="list-style-type: none">• Update the supported frequencies;• Update the TTFF;• Add chapter 3.5: Recommended PCB Package Design;• Optimize Chapter 3.2 Antenna Feed Design;• Optimize Chapter 3.3 Power-on and Power-off	2023-04

UM980 User Manual

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Foreword

This document describes the information of the hardware, package, specification and the use of Unicore UM980 modules.

Target Readers

This document applies to technicians who possess the expertise on GNSS receivers.

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1 Introduction

UM980 is a new generation of GNSS high precision RTK positioning module from Unicore. It supports all constellations and all frequencies, and can simultaneously track BDS B1I/B2I/B3I/B1C/B2a/B2b, GPS L1/L2/L5, GLONASS G1/G2/G3, Galileo E1/E5a/E5b/E6, QZSS L1/L2/L5, NavIC L5 and SBAS. The module is mainly used in surveying and mapping, precise agriculture, UAVs, and autonomous robots.

UM980 is based on NebulasIV™, a GNSS SoC which integrates the RF-baseband and high precision algorithm. Besides, the SoC integrates a dual-core CPU, a high speed floating point processor and an RTK co-processor with 22 nm low power design, and it supports 1408 super channels. All these above enable stronger signal processing.

With the built-in JamShield adaptive anti-jamming technology, UM980 can fulfill a strengthening RTK engine solution of multi-mode multi-frequency, which ensures a good performance on RTK initialization speed, measurement accuracy and reliability even in the most challenging environments such as urban canyons and tree shades.

Furthermore, UM980 supports abundant interfaces such as UART, I²C*, SPI*, as well as 1PPS, EVENT, CAN*, which meets the customers' needs in different applications.



Figure 1-1 UM980 Module

* I²C, SPI, CAN: reserved interfaces, not supported currently

1.1 Key Features

- Based on the new generation GNSS SoC -NebulasIV™, with RF-baseband and high precision algorithm integrated
- 17 mm × 22 mm × 2.6 mm, surface-mount device
- Supports all-constellation multi-frequency on-chip RTK positioning solution
- Supports BDS B1I/B2I/B3I/B1C/B2a/B2b + GPS L1/L2/L5 + GLONASS G1/G2/G3 + Galileo E1/E5a/E5b/E6 + QZSS L1/L2/L5 + NavIC L5 + SBAS
- All-constellation multi-frequency RTK engine and advanced RTK processing technology
- Instantaneous RTK initialization technology
- Independent tracking of different frequencies, and 60 dB narrowband anti-jamming technology

1.2 Key Specifications

Table 1-1 Technical Specifications

Basic Information	
Channels	1408 channels, based on NebulasIV™
Constellations	BDS/GPS/GLONASS/Galileo/QZSS
Frequencies	BDS: B1I, B2I, B3I, B1C, B2a, B2b
	GPS: L1 C/A, L1C, L2P (Y), L2C, L5
	GLONASS: G1, G2, G3
	Galileo: E1, E5a, E5b, E6
	QZSS: L1, L2, L5
	NavIC: L5
Power	
Voltage	+3.0 V ~ +3.6 V DC
Power Consumption	480 mW (Typical)

Performance				
Positioning Accuracy	Single Point Positioning ¹ (RMS)		Horizontal: 1.5 m	
			Vertical: 2.5 m	
	DGPS (RMS) ^{1,2}		Horizontal: 0.4 m	
			Vertical: 0.8 m	
	RTK (RMS) ^{1,2}		Horizontal: 0.8 cm + 1 ppm	
			Vertical: 1.5 cm + 1 ppm	
Observation Accuracy (RMS)	BDS	GPS	GLONASS	Galileo
B1I/B1C/L1C/L1 C/A/G1/E1 Pseudorange	10 cm	10 cm	10 cm	10 cm
B1I/B1C/L1C/L1 C/A/G1/E1 Carrier Phase	1 mm	1 mm	1 mm	1 mm
B3I/L2P(Y)/L2C/G2/E6 Pseudorange	10 cm	10 cm	10 cm	10 cm
B3I/L2P(Y)/L2C/G2/E6 Carrier Phase	1 mm	1 mm	1 mm	1 mm
B2I/B2a/B2b/L5/G3/E5a/E5b Pseudorange	10 cm	10 cm	10 cm	10 cm
B2I/B2a/B2b/L5/G3/E5a/E5b Carrier Phase	1 mm	1 mm	1 mm	1 mm
Time Pulse Accuracy (RMS)	20 ns			
Velocity Accuracy ³ (RMS)	0.03 m/s			

¹ Test results may be biased due to atmospheric conditions, baseline length, GNSS antenna type, multipath, number of visible satellites, and satellite geometry

² The measurement uses a 1 km baseline and a receiver with good antenna performance, regardless of possible errors of antenna phase center offset

³ Open sky, unobstructed scene, 99% @ static

Time to First Fix ⁴ (TTFF)	Cold Start < 12 s
	Hot Start < 4 s
Initialization Time ¹	< 5 s (Typical)
Initialization Reliability ¹	> 99.9%
Data Update Rate	50 Hz ⁵ Positioning
Differential Data	RTCM 3.X
Data Format	NMEA-0183, Unicore
Physical Characteristics	
Package	54 pin LGA
Dimensions	22 mm × 17 mm × 2.6 mm
Weight	1.88 g ± 0.03 g
Environmental Specifications	
Operating Temperature	-40 °C ~ +85 °C
Storage Temperature	-55 °C ~ +95 °C
Humidity	95% No condensation
Vibration	GJB150.16A-2009, MIL-STD-810F
Shock	GJB150.18A-2009, MIL-STD-810F
Functional Ports	
UART × 3	
I ² C* × 1	
SPI* × 1	Slave
CAN* × 1	Shared with UART3

* I²C, SPI, CAN: reserved interfaces, not supported currently

⁴ -130dBm @ more than 12 available satellites

⁵ Supports 50 Hz after firmware upgrade

1.3 Block Diagram

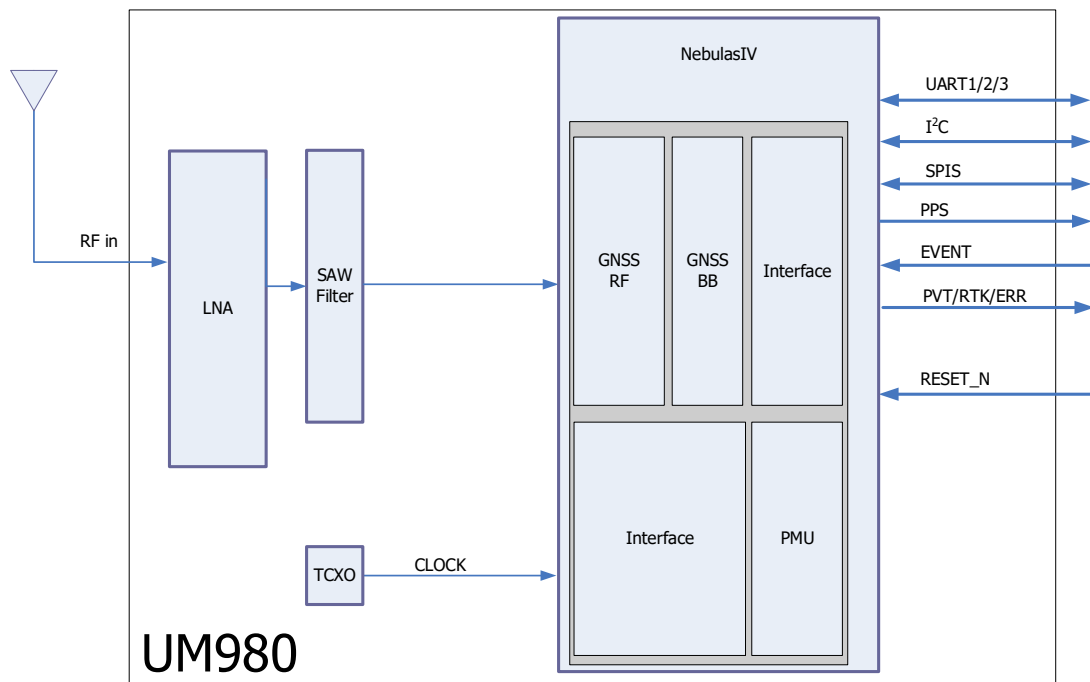


Figure 1-2 UM980 Block Diagram

- **RF Part**

The receiver gets filtered and enhanced GNSS signal from the antenna via a coaxial cable. The RF part converts the RF input signals into the IF signals, and converts IF analog signals into digital signals required for NebulasIV™ chip (UC9810).

- **NebulasIV™ SoC (UC9810)**

NebulasIV (UC9810) is UNICORECOMM's new generation high precision GNSS SoC with 22 nm low power design, supporting all constellations all frequencies and 1408 super channels. It integrates a dual-core CPU, a high speed floating point processor and an RTK co-processor, which can fulfill the high precision baseband processing and RTK positioning independently.

- **External Interfaces**

The external interfaces of UM980 include UART, I²C*, SPI*, CAN*, PPS, EVENT, RTK_STAT, PVT_STAT, ERR_STAT, RESET_N, etc.

* I²C, SPI, CAN: reserved interfaces, not supported currently

2 Hardware

2.1 Pin Definition

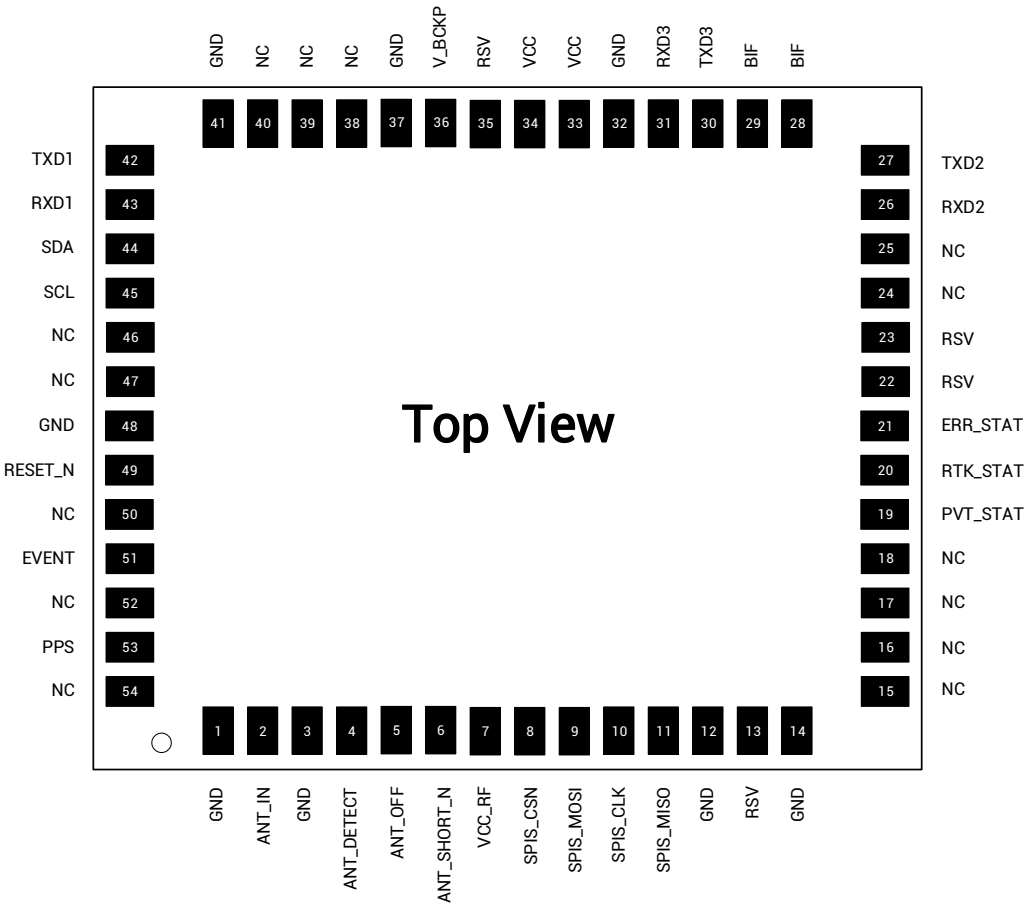


Figure 2-1 UM980 Pin Definition

Table 2-1 Pin Description

No.	Pin	I/O	Description
1	GND	—	Ground
2	ANT_IN	I	GNSS antenna signal input
3	GND	—	Ground
4	ANT_DETECT	I	Antenna signal detection
5	ANT_OFF	O	Disable external LNA

No.	Pin	I/O	Description
6	ANT_SHORT_N	I	Antenna short circuit detection; active low
7	VCC_RF ⁶	O	External LNA power supply
8	SPIS_CSN	I	Chip select pin for SPI slave
9	SPIS_MOSI	I	Master Out / Slave In. This pin is used to receive data in slave mode.
10	SPIS_CLK	I	Clock input pin for SPI slave
11	SPIS_MISO	O	Master In / Slave Out. This pin is used to transmit data in slave mode.
12	GND	—	Ground
13	RSV	—	Reserved
14	GND	—	Ground
15	NC	—	No connection inside
16	NC	—	No connection inside
17	NC	—	No connection inside
18	NC	—	No connection inside
19	PVT_STAT	O	PVT status: active high; outputs high when positioning and low when not positioning
20	RTK_STAT	O	RTK status: active high; outputs high for RTK fixed solution and low for other positioning status or no positioning

⁶ Not recommended to take VCC_RF as ANT_BIAS to feed the antenna. See section 3.2 for more details.

No.	Pin	I/O	Description
21	ERR_STAT	O	Error status: active high; outputs high when failing self-test, and low when passing self-test
22	RSV	—	Reserved, recommended to be floating
23	RSV	—	Reserved, recommended to be floating
24	NC	—	No connection inside
25	NC	—	No connection inside
26	RXD2	I	COM2 input, LVTTTL level
27	TXD2	O	COM2 output, LVTTTL level
28	BIF	—	Built-in function; recommended to add a through-hole testing point and a 10 kΩ pull-up resistor; cannot connect ground or power supply, and cannot input/output data, but can be floating
29	BIF	—	Built-in function; recommended to add a through-hole testing point and a 10 kΩ pull-up resistor; cannot connect ground or power supply, and cannot input/output data, but can be floating
30	TXD3	O	COM3 output, which can be used as CAN TXD, LVTTTL level
31	RXD3	I	COM3 input, which can be used as CAN RXD, LVTTTL level
32	GND	—	Ground
33	VCC	I	Power supply
34	VCC	I	Power supply
35	RSV	—	Reserved

No.	Pin	I/O	Description
36	V_BCKP	I	When the main power supply VCC is cut off, V_BCKP supplies power to RTC and relevant register. Level requirement: 2.0 V ~ 3.6 V, and the working current should be less than 60 μ A at 25 °C. If you do not use the hot start function, connect V_BCKP to VCC. Do NOT connect it to ground or leave it floating.
37	GND	—	Ground
38	NC	—	No connection inside
39	NC	—	No connection inside
40	NC	—	No connection inside
41	GND	—	Ground
42	TXD1	O	COM1 output, LVTTTL level
43	RXD1	I	COM1 input, LVTTTL level
44	SDA	I/O	I ² C data
45	SCL	I/O	I ² C clock
46	NC	—	No connection inside
47	NC	—	No connection inside
48	GND	—	Ground
49	RESET_N	I	System reset; active Low. The active time should be no less than 5 ms.
50	NC	—	No connection inside
51	EVENT	I	Event mark input, with adjustable frequency and polarity
52	NC	—	No connection inside

No.	Pin	I/O	Description
53	PPS	O	Pulse per second, with adjustable pulse width and polarity
54	NC	—	No connection inside

2.2 Electrical Specifications

2.2.1 Absolute Maximum Ratings

Table 2-2 Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit
Power Supply Voltage	VCC	-0.3	3.6	V
Input Voltage	V _{in}	-0.3	3.6	V
GNSS Antenna Signal Input	ANT_IN	-0.3	6	V
Antenna RF Input Power	ANT_IN input power		+10	dBm
External LNA Power Supply	VCC_RF	-0.3	3.6	V
VCC_RF Output Current	ICC_RF		100	mA
Storage Temperature	T _{stg}	-55	95	°C

2.2.2 Operating Conditions

Table 2-3 Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Power Supply Voltage ⁷	VCC	3.0	3.3	3.6	V	
Maximum VCC Ripple	V _{rpp}	0		50	mV	
Working Current ⁸	I _{opr}		145	180	mA	VCC=3.3 V

⁷ The voltage range of VCC (3.0 V ~ 3.6 V) has already included the ripple voltage.

⁸ Since the product has capacitors inside, inrush current occurs during power-on. You should evaluate in the actual environment in order to check the effect of the supply voltage drop caused by inrush

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
VCC_RF Output Voltage	VCC_RF		VCC-0.1		V	
VCC_RF Output Current	ICC_RF			50	mA	
Operating Temperature	T _{opr}	-40		85	°C	
Power Consumption	P		480		mW	

2.2.3 IO Threshold

Table 2-4 IO Threshold

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Low Level Input Voltage	V _{in_low}	0		0.6	V	
High Level Input Voltage	V _{in_high}	VCC × 0.7		VCC + 0.2	V	
Low Level Output Voltage	V _{out_low}	0		0.45	V	I _{out} = 2 mA
High Level Output Voltage	V _{out_high}	VCC - 0.45		VCC	V	I _{out} = 2 mA

2.2.4 Antenna Feature

Table 2-5 Antenna Feature

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Optimum Input Gain	G _{ant}	18	30	36	dB	

current in the system.

2.3 Dimensions

Table 2-6 Dimensions

Parameter	Min. (mm)	Typ. (mm)	Max. (mm)
A	21.80	22.00	22.50
B	16.80	17.00	17.50
C	2.40	2.60	2.80
D	3.75	3.85	3.95
E	0.95	1.05	1.15
F	1.80	1.90	2.00
G	1.00	1.10	1.20
H	0.70	0.80	0.90
K	1.40	1.50	1.60
M	3.55	3.65	3.75
N	3.15	3.25	3.35
P	2.00	2.10	2.20
R	1.00	1.10	1.20
X	0.72	0.82	0.92

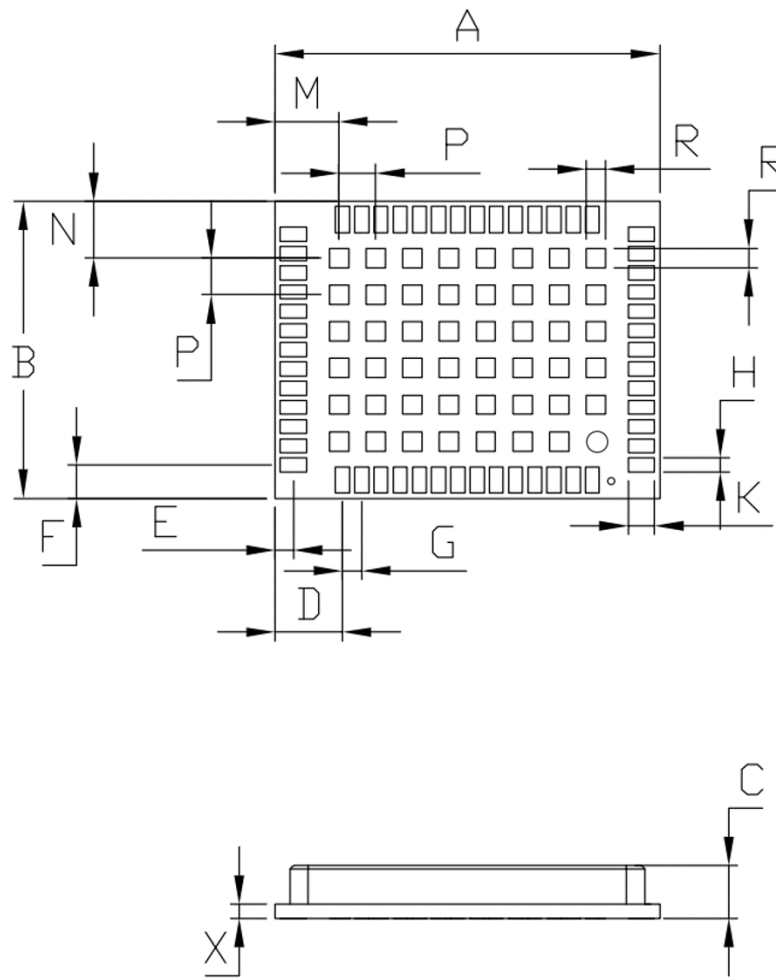


Figure 2-2 UM980 Mechanical Dimensions

3 Hardware Design

3.1 Recommended Minimal Design

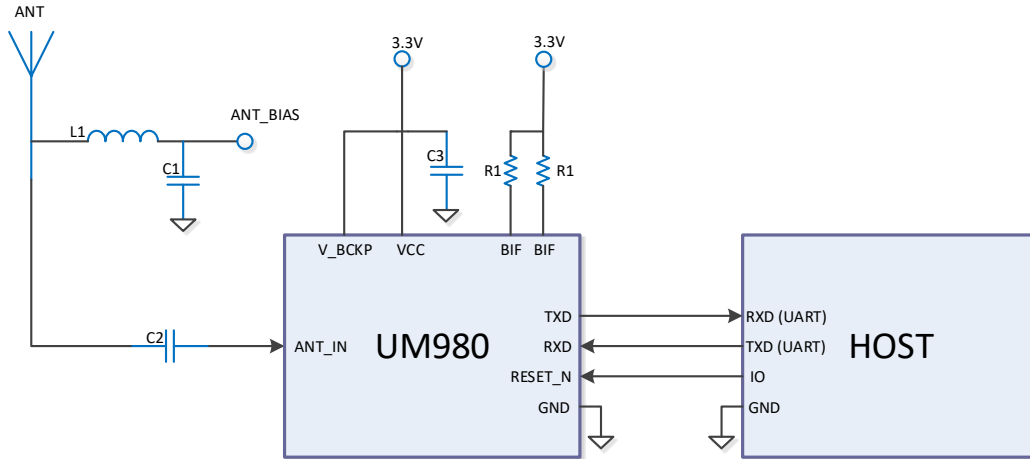


Figure 3-1 Recommended Minimal Design

L1: 68 nH RF inductor in 0603 package is recommended

C1: 100 nF + 100 pF capacitors connected in parallel is recommended

C2: 100 pF capacitor is recommended

C3: $N \times 10 \mu\text{F} + 1 \times 100 \text{ nF}$ capacitors connected in parallel is recommended, and the total inductance should be no less than $30 \mu\text{F}$

R1: 10 kΩ resistor is recommended

3.2 Antenna Feed Design

UM980 just supports feeding the antenna from the outside of the module rather than from the inside. It is recommended to use devices with high power and that can withstand high voltage. Gas discharge tube, varistor, TVS tube and other high-power protective devices may also be used in the power supply circuit to further protect the module from lightning strike and surge.

- ⚠ If the antenna feed supply ANT_BIAS and the module's main supply VCC use the same power rail, the ESD, surge and overvoltage from the antenna will have an effect on VCC, which may cause damage to the module. Therefore, it is recommended to design an independent power rail for the ANT_BIAS to reduce the possibility of module damage.

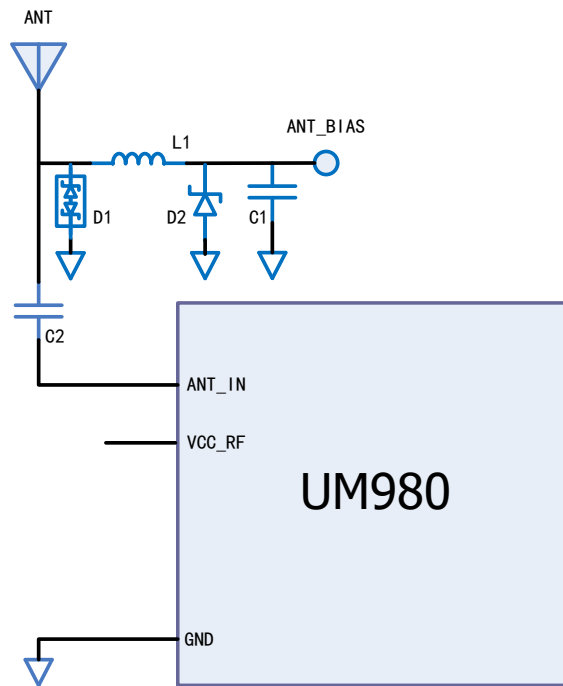


Figure 3-2 UM980 External Antenna Feed Reference Circuit

Notes:

- L1: feed inductor, 68 nH RF inductor in 0603 package is recommended
- C1: decoupling capacitor, recommended to connect two capacitors of 100 nF/100 pF in parallel
- C2: DC blocking capacitor, recommended 100 pF capacitor
- It is not recommended to take VCC_RF as ANT_BIAS to feed the antenna (VCC_RF is not optimized for anti-lightning strike, anti-surge and over current protection due to the compact size of the module)
- D1: ESD diode, choose the ESD protection device that supports high frequency signals (above 2000 MHz)
- D2: TVS diode, choose the TVS diode with appropriate clamping specification according to the requirement of feed voltage and antenna withstand voltage

3.3 Power-on and Power-off

VCC

- The VCC initial level when power-on should be less than 0.4 V.
- The VCC ramp when power-on should be monotonic, without plateaus.
- The voltages of undershoot and ringing should be within 5% VCC.
- VCC power-on waveform: The time interval from 10% rising to 90% must be within 100 μ s ~1 ms.
- Power-on time interval: The time interval between the power-off ($V_{CC} < 0.4$ V) to the next power-on must be larger than 500 ms.

V_BCKP

- The V_BCKP initial level when power-on should be less than 0.4 V.
- The V_BCKP ramp when power-on should be monotonic, without plateaus.
- The voltages of undershoot and ringing should be within 5% V_BCKP.
- V_BCKP power-on waveform: The time interval from 10% rising to 90% must be within 100 μ s ~1 ms.
- Power-on time interval: The time interval between the power-off ($V_{BCKP} < 0.4$ V) to the next power-on must be larger than 500 ms.

3.4 Grounding and Heat Dissipation

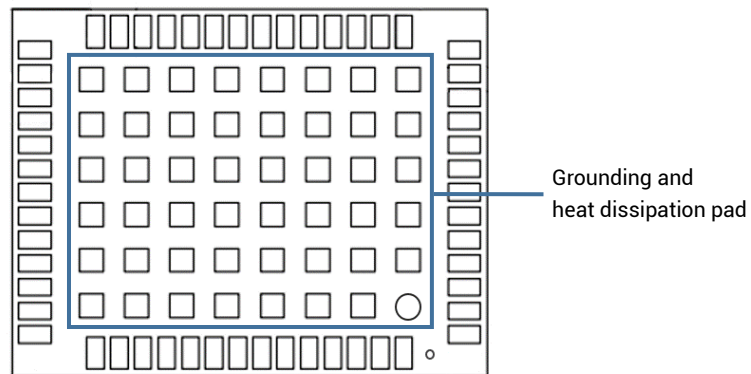


Figure 3-3 Grounding and Heat Dissipation Pad (Bottom View)

The 48 pads in the rectangle in Figure 3-3 are for grounding and heat dissipation. In the PCB design, the pads should be connected to a large sized ground to strengthen the heat dissipation.

3.5 Recommended PCB Package Design

See the following figure for the recommended PCB package design.

Unit: mm

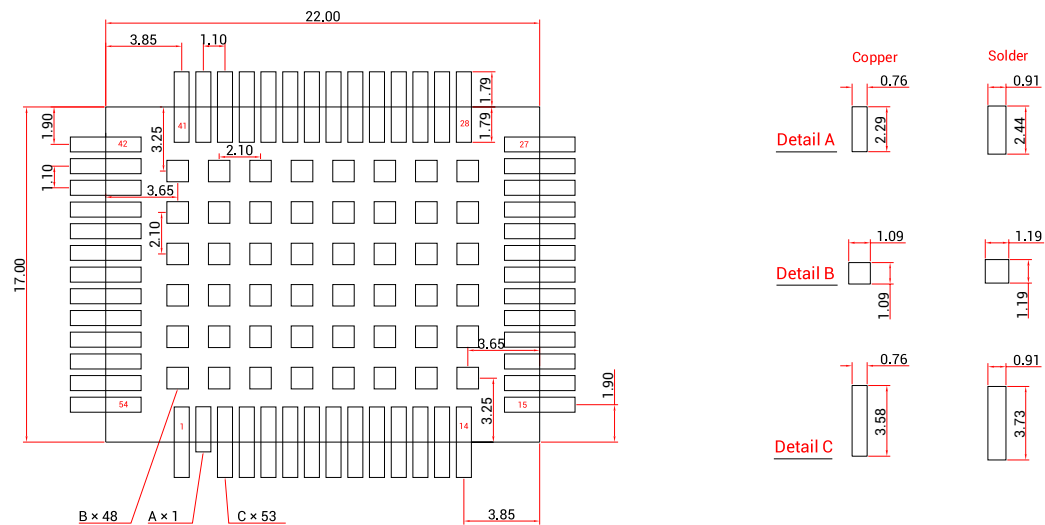


Figure 3-4 Recommended PCB Package Design

Notes:

For the convenience of testing, the soldering pads of the pins are designed long, exceeding the module border much more. For example:

- The pads denoted as detail C are 1.79 mm longer than the module border.
- The pad denoted as detail A is 0.50 mm longer than the module border. It is relatively short as it is an RF pin pad, so we hope the trace on the surface is as short as possible to reduce the impact of external interference on the RF signals.

4 Production Requirement

Recommended soldering temperature curve is as follows:

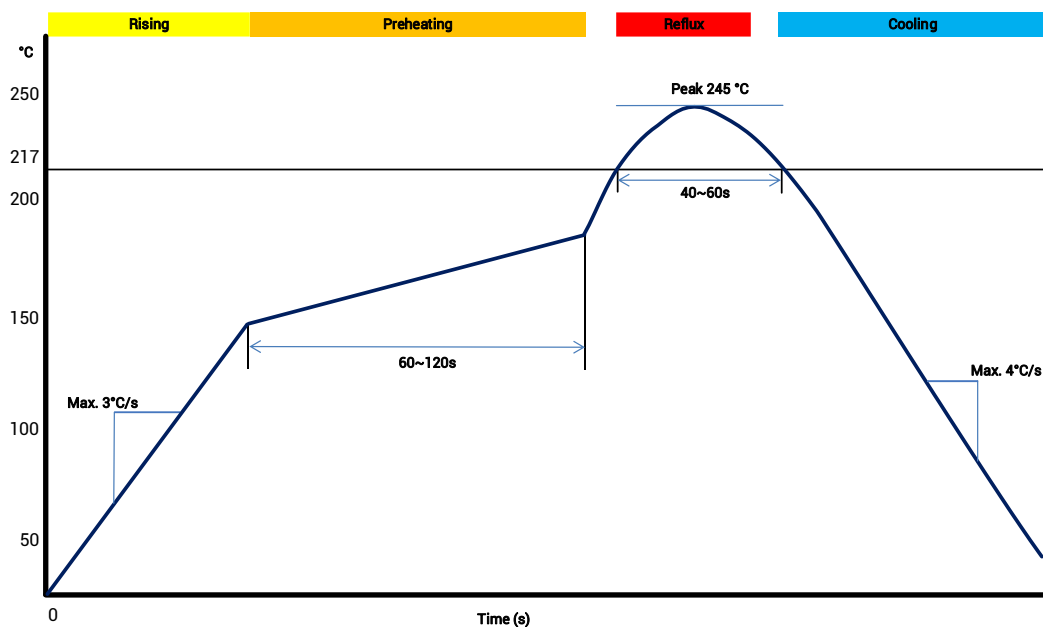


Figure 4-1 Soldering Temperature (Lead-free)

Temperature Rising Stage

- Rising slope: Max. 3 °C/s
- Rising temperature range: 50 °C ~ 150 °C

Preheating Stage

- Preheating time: 60s ~ 120 s
- Preheating temperature range: 150 °C ~ 180 °C

Reflux Stage

- Over melting temperature (217 °C) time: 40s ~ 60 s
- Peak temperature for soldering: no higher than 245 °C

Cooling Stage

- Cooling slope: Max. 4 °C / s



- In order to prevent falling off during soldering of the module, do not solder it on the back of the board during design, and it is not recommended to go through soldering cycle twice.
- The setting of soldering temperature depends on many factors of the factory, such as board type, solder paste type, solder paste thickness etc. Please also refer to the relevant IPC standards and indicators of solder paste.
- Since the lead soldering temperature is relatively low, if using this method, please give priority to other components on the board.
- The opening of the stencil needs to meet your design requirement and comply with the examine standards. The thickness of the stencil is recommended to be 0.15mm.

5 Packaging

5.1 Label Description



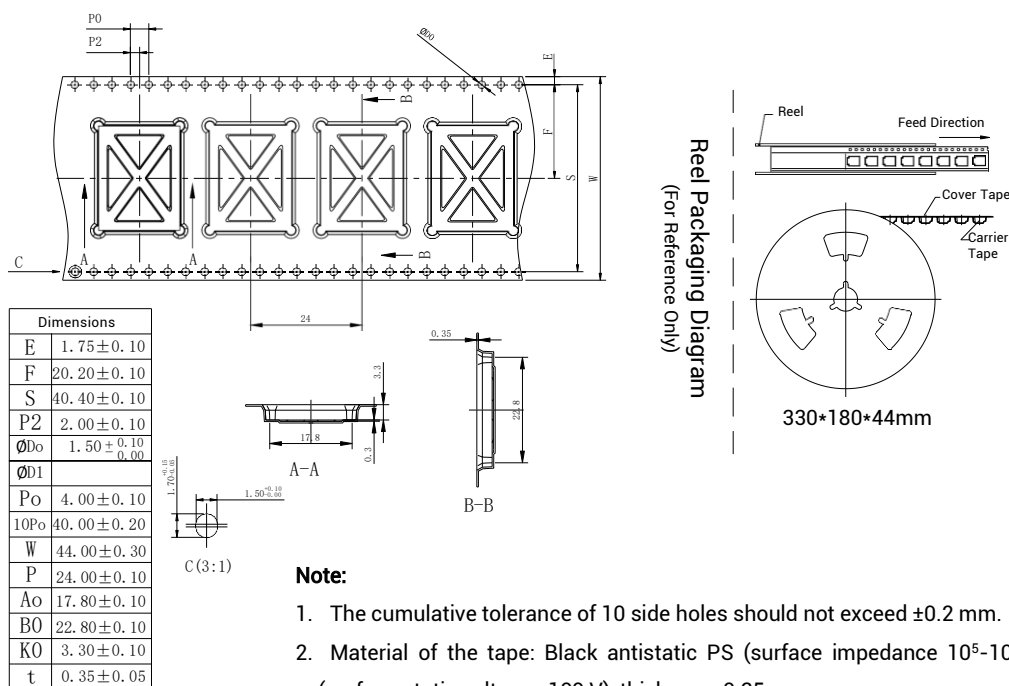
Figure 5-1 Label Description

5.2 Product Packaging

The UM980 module uses carrier tape and reel (suitable for mainstream surface mount devices), packaged in vacuum-sealed aluminum foil antistatic bags, with a desiccant inside to prevent moisture. When using reflow soldering process to solder modules, please strictly comply with IPC standard to conduct temperature and humidity control on the modules. As packaging materials such as the carrier tape can only withstand the temperature of 55 degrees Celsius, modules shall be removed from the package during baking.



Figure 5-2 UM980 Package



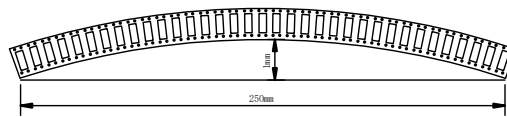


Figure 5-3 UM980 Reel Package Diagram

Table 5-1 Package Description

Item	Description
Module Number	250 pieces/reel
Reel Size	Tray: 13" External diameter: 330 ± 2 mm, Internal diameter: 180 ± 2 mm, Width: 44.5 ± 0.5 mm Thickness: 2.0 ± 0.2 mm
Carrier Tape	Space between (center-to-center distance): 24 mm

Before surface mounting, make sure that the color of the 30% circle on the HUMIDITY INDICATOR is blue (see Figure 5-4). If the color of the 20% circle is pink and the color of the 30% circle is lavender (see Figure 5-5), you must bake the module until it turns to blue. The UM980 is rated at MSL level 3. Please refer to the IPC/JEDEC J-STD-033 standards for the package and operation requirements. You may also access to the website www.jedec.org to get more information.

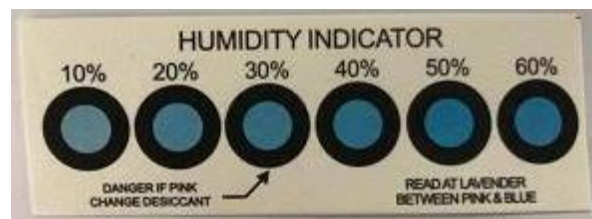


Figure 5-4 Normal Humidity Indication

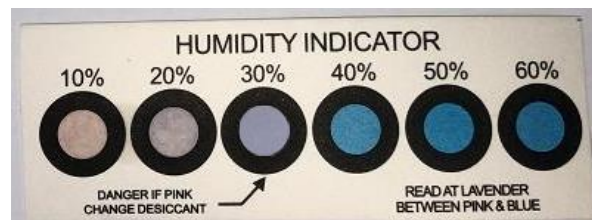


Figure 5-5 Abnormal Humidity Indication

The shelf life of the UM980 module packaged in vacuum-sealed aluminum foil antistatic bags is one year.

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